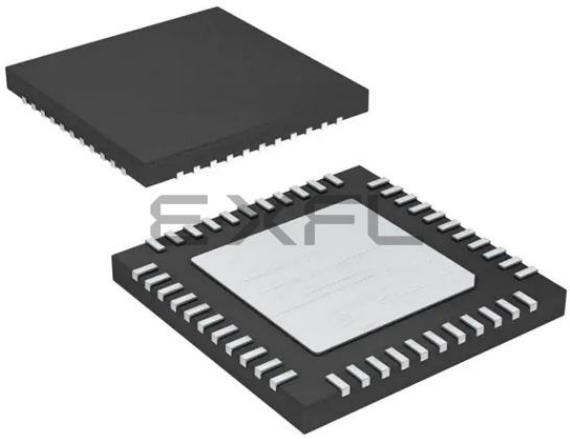

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	34
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	2.15V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f46j13-i-ml

1.0 DEVICE OVERVIEW

This document contains device-specific information for the following devices:

- PIC18F26J13
- PIC18F27J13
- PIC18F46J13
- PIC18F47J13
- PIC18LF26J13
- PIC18LF27J13
- PIC18LF46J13
- PIC18LF47J13

1.1 Core Features

1.1.1 XLP TECHNOLOGY

All of the devices in the PIC18F47J13 Family incorporate a range of features that can significantly reduce power consumption during operation. Key features are:

- **Alternate Run Modes:** By clocking the controller from the Timer1 source or the internal RC oscillator, power consumption during code execution can be reduced by as much as 90%.
- **Multiple Idle Modes:** The controller can also run with its CPU core disabled but the peripherals still active. In these states, power consumption can be reduced even further, to as little as 4% of normal operational requirements.
- **On-the-Fly Mode Switching:** The power-managed modes are invoked by user code during operation, allowing the users to incorporate power-saving ideas into their application's software design.
- **Deep Sleep:** The 2.5V internal core voltage regulator on F parts can be shutdown to cut power consumption to as low as 15 nA (typical). Certain features can remain operating during Deep Sleep, such as the Real-Time Clock Calendar.
- **Ultra Low Power Wake-Up:** Waking from Sleep or Deep Sleep modes after a period of time can be done without an oscillator/clock source, saving power for applications requiring periodic activity.

1.1.2 OSCILLATOR OPTIONS AND FEATURES

All of the devices in the PIC18F47J13 Family offer five different oscillator options, allowing users a range of choices in developing application hardware. These include:

- Two Crystal modes, using crystals or ceramic resonators.
- Two External Clock modes, offering the option of a divide-by-4 clock output.
- An internal oscillator block, which provides an 8 MHz clock and an INTRC source (approximately 31 kHz, stable over temperature and V_{DD}), as well as a range of six user selectable clock frequencies, between 125 kHz to 4 MHz, for a total of eight clock frequencies. This option frees an oscillator pin for use as an additional general purpose I/O.
- A Phase Lock Loop (PLL) frequency multiplier available to the high-speed crystal, and external and internal oscillators, providing a clock speed up to 48 MHz.

The internal oscillator block provides a stable reference source that gives the PIC18F47J13 Family additional features for robust operation:

- **Fail-Safe Clock Monitor:** This option constantly monitors the main clock source against a reference signal provided by the internal oscillator. If a clock failure occurs, the controller is switched to the internal oscillator, allowing for continued low-speed operation or a safe application shutdown.
- **Two-Speed Start-up:** This option allows the internal oscillator to serve as the clock source from Power-on Reset (POR), or wake-up from Sleep mode, until the primary clock source is available.

4.7 Ultra Low-Power Wake-up

The Ultra Low-Power Wake-up (ULPWU) on RA0 allows a slow falling voltage to generate an interrupt-on-change without excess current consumption.

Follow these steps to use this feature:

1. Configure a remappable output pin to output the ULPOUT signal.
2. Map an INTx interrupt-on-change input function to the same pin as used for the ULPOUT output function. Alternatively, in Step 1, configure ULPOUT to output onto a PORTB interrupt-on-change pin.
3. Charge the capacitor on RA0 by configuring the RA0 pin to an output and setting it to '1'.
4. Enable interrupt-on-change (PIE bit) for the corresponding pin selected in Step 2.
5. Stop charging the capacitor by configuring RA0 as an input.
6. Discharge the capacitor by setting the ULPEN and ULPSINK bits in the WDTCON register.
7. Configure Sleep mode.
8. Enter Sleep mode.

When the voltage on RA0 drops below V_{IL}, an interrupt will be generated, which will cause the device to wake-up and execute the next instruction.

This feature provides a low-power technique for periodically waking up the device from Sleep mode. The time-out is dependent on the discharge time of the RC circuit on RA0.

When the ULPWU module causes the device to wake-up from Sleep mode, the ULPLVL (WDTCON<5>) bit is set. When the ULPWU module causes the device to wake-up from Deep Sleep, the DSULP (DSWAKEL<5>) bit is set. Software can check these bits upon wake-up to determine the wake-up source. Also in Sleep mode, only the remappable output function, ULPWU, will output this bit value to an RPn pin for externally detecting wake-up events.

See Example 4-1 for initializing the ULPWU module.

Note:	For module related bit definitions, see the WDTCON register in **Section 27.2 "Watchdog Timer (WDT)"** and the DSWAKEL register (Register 4-6).

9.3 PIE Registers

The PIE registers contain the individual enable bits for the peripheral interrupts. Due to the number of peripheral interrupt sources, there are three Peripheral Interrupt Enable registers (PIE1, PIE2, PIE3). When IPEN = 0, the PEIE bit must be set to enable any of these peripheral interrupts.

REGISTER 9-9: PIE1: PERIPHERAL INTERRUPT ENABLE REGISTER 1 (ACCESS F9Dh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PMPIE(1)	ADIE	RC1IE	TX1IE	SSP1IE	CCP1IE	TMR2IE	TMR1IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **PMPIE:** Parallel Master Port Read/Write Interrupt Enable bit(1)
1 = Enables the PMP read/write interrupt
0 = Disables the PMP read/write interrupt

bit 6 **ADIE:** A/D Converter Interrupt Enable bit
1 = Enables the A/D interrupt
0 = Disables the A/D interrupt

bit 5 **RC1IE:** EUSART1 Receive Interrupt Enable bit
1 = Enables the EUSART1 receive interrupt
0 = Disables the EUSART1 receive interrupt

bit 4 **TX1IE:** EUSART1 Transmit Interrupt Enable bit
1 = Enables the EUSART1 transmit interrupt
0 = Disables the EUSART1 transmit interrupt

bit 3 **SSP1IE:** Master Synchronous Serial Port 1 Interrupt Enable bit
1 = Enables the MSSP1 interrupt
0 = Disables the MSSP1 interrupt

bit 2 **CCP1IE:** ECCP1 Interrupt Enable bit
1 = Enables the ECCP1 interrupt
0 = Disables the ECCP1 interrupt

bit 1 **TMR2IE:** TMR2 to PR2 Match Interrupt Enable bit
1 = Enables the TMR2 to PR2 match interrupt
0 = Disables the TMR2 to PR2 match interrupt

bit 0 **TMR1IE:** TMR1 Overflow Interrupt Enable bit
1 = Enables the TMR1 overflow interrupt
0 = Disables the TMR1 overflow interrupt

Note 1: These bits are unimplemented on 28-pin devices.

TABLE 10-5: PORTB I/O SUMMARY

Pin	Function	TRIS Setting	I/O	I/O Type	Description
RB0/AN12/ C3IND/INT0/ RP3	RB0	1	I	TTL	PORTB<0> data input; weak pull-up when the $\overline{\text{RBPU}}$ bit is cleared. Disabled when analog input is enabled.(1)
		0	O	DIG	LATB<0> data output; not affected by an analog input.
	AN12	1	I	ANA	A/D Input Channel 12.(1)
	C3IND	1	I	ANA	Comparator 3 Input D.
	INT0	1	I	ST	External Interrupt 0 input.
	RP3	1	I	ST	Remappable Peripheral Pin 3 input.
		0	O	DIG	Remappable Peripheral Pin 3 output.
RB1/AN10/ C3INC/PMBE/ RTCC/RP4	RB1	1	I	TTL	PORTB<1> data input; weak pull-up when the $\overline{\text{RBPU}}$ bit is cleared. Disabled when an analog input is enabled.(1)
		0	O	DIG	LATB<1> data output; not affected by an analog input.
	AN10	1	I	ANA	A/D Input Channel 10.(1)
	C3INC	1	I	ANA	Comparator 3 Input C.
	PMBE(3)	x	O	DIG	Parallel Master Port byte enable.
	RTCC	0	O	DIG	Asynchronous serial transmit data output (USART module).
	RP4	1	I	ST	Remappable Peripheral Pin 4 input.
		0	O	DIG	Remappable Peripheral Pin 4 output.
RB2/AN8/ C2INC/CTED1/ PMA3/REFO/ RP5	RB2	1	I	TTL	PORTB<2> data input; weak pull-up when the $\overline{\text{RBPU}}$ bit is cleared. Disabled when an analog input is enabled.(1)
		0	O	DIG	LATB<2> data output; not affected by an analog input.
	AN8	1	I	ANA	A/D Input Channel 8.(1)
	C2INC	1	I	ANA	Comparator 2 Input C.
	CTED1	1	I	ST	CTMU Edge 1 input.
	PMA3(3)	x	O	DIG	Parallel Master Port address.
	REFO	0	O	DIG	Reference output clock.
	RP5	1	I	ST	Remappable Peripheral Pin 5 input.
		0	O	DIG	Remappable Peripheral Pin 5 output.
RB3/AN9/ C3INA/CTED2/ PMA2/RP6	RB3	0	O	DIG	LATB<3> data output; not affected by analog input.
		1	I	TTL	PORTB<3> data input; weak pull-up when the $\overline{\text{RBPU}}$ bit is cleared. Disabled when analog input is enabled.(1)
	AN9	1	I	ANA	A/D Input Channel 9.(1)
	C3INA	1	I	ANA	Comparator 3 Input A.
	CTED2	1	I	ST	CTMU Edge 2 input.
	PMA2(3)	x	O	DIG	Parallel Master Port address.
	RP6	1	I	ST	Remappable Peripheral Pin 6 input.
		0	O	DIG	Remappable Peripheral Pin 6 output.

Legend: DIG = Digital level output; TTL = TTL input buffer; ST = Schmitt Trigger input buffer; ANA = Analog level input/output; x = Don't care (TRISx bit does not affect port direction or is overridden for this option)

Note 1: Pins are configured as analog inputs by default on POR. Using these pins for digital inputs requires setting the appropriate bits in the ANCON1 register.

2: All other pin functions are disabled when ICSP™ or ICD is enabled.

3: Only on 44-pin devices (PIC18F46J13, PIC18F47J13, PIC18LF46J13 and PIC18LF47J13).

4: Only on 28-pin devices (PIC18F26J13, PIC18F27J13, PIC18LF26J13 and PIC18LF27J13).

17.1.4 RTCEN BIT WRITE

An attempt to write to the RTCEN bit while RTCWREN = 0 will be ignored. RTCWREN must be set before a write to RTCEN can take place.

Like the RTCEN bit, the RTCVALH and RTCVALL registers can only be written to when RTCWREN = 1. A write to these registers, while RTCWREN = 0, will be ignored.

17.2 Operation

17.2.1 REGISTER INTERFACE

The register interface for the RTCC and alarm values is implemented using the Binary Coded Decimal (BCD) format. This simplifies the firmware when using the module, as each of the digits is contained within its own 4-bit value (see Figure 17-2 and Figure 17-3).

FIGURE 17-2: TIMER DIGIT FORMAT

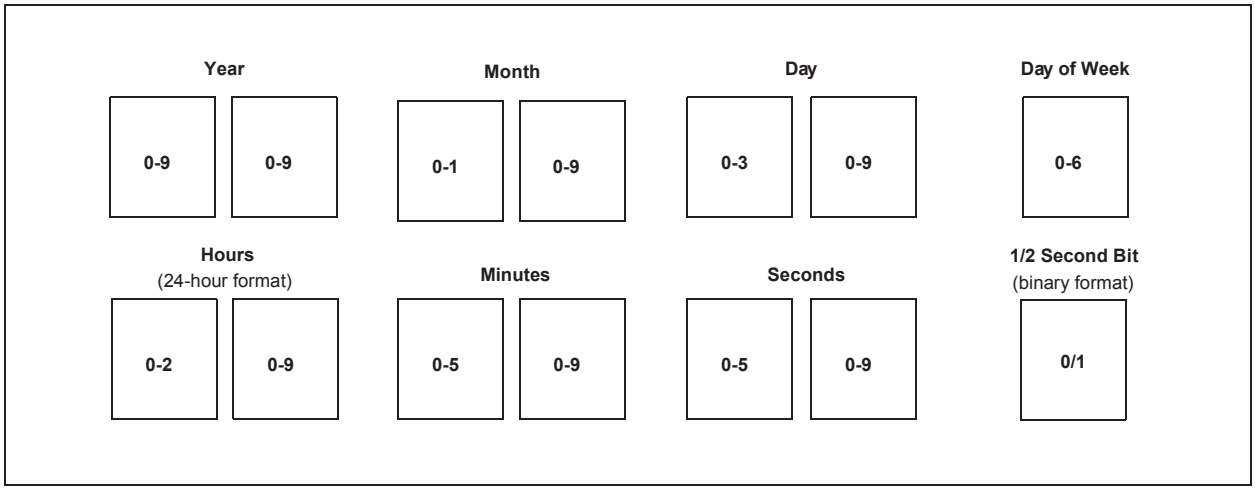
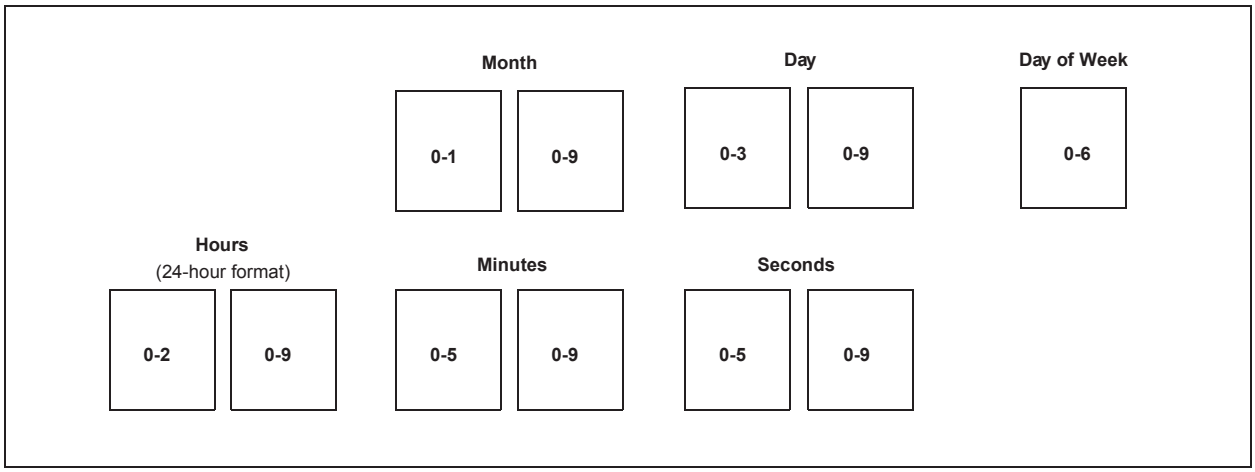


FIGURE 17-3: ALARM DIGIT FORMAT



17.3 Alarm

The alarm features and characteristics are:

- Configurable from half a second to one year
- Enabled using the ALRMEN bit (ALRMCFG<7>, Register 17-4)
- Offers one time and repeat alarm options

17.3.1 CONFIGURING THE ALARM

The alarm feature is enabled using the ALRMEN bit.

This bit is cleared when an alarm is issued. The bit will not be cleared if the CHIME bit = 1 or if ALRMRPT ≠ 0.

The interval selection of the alarm is configured through the ALRMCFG (AMASK<3:0>) bits (see Figure 17-5). These bits determine which and how many digits of the alarm must match the clock value for the alarm to occur.

The alarm can also be configured to repeat based on a preconfigured interval. The number of times this occurs, after the alarm is enabled, is stored in the ALRMRPT register.

Note:	While the alarm is enabled (ALRMEN = 1), changing any of the registers, other than the RTCCAL, ALRMCFG and ALRMRPT registers, and the CHIME bit, can result in a false alarm event leading to a false alarm interrupt. To avoid this, only change the timer and alarm values while the alarm is disabled (ALRMEN = 0). It is recommended that the ALRMCFG and ALRMRPT registers and CHIME bit be changed when RTCSYNC = 0.

FIGURE 17-5: ALARM MASK SETTINGS

Alarm Mask Setting AMASK<3:0>	Day of the Week	Month	Day	Hours	Minutes	Seconds
0000 – Every half second 0001 – Every second						
0010 – Every 10 seconds						s
0011 – Every minute						s s
0100 – Every 10 minutes					m	s s
0101 – Every hour					m m	s s
0110 – Every day				h h	m m	s s
0111 – Every week	d			h h	m m	s s
1000 – Every month			d d	h h	m m	s s
1001 – Every year(1)		m m	d d	h h	m m	s s

Note 1: Annually, except when configured for February 29.

The WUE bit is automatically cleared once a low-to-high transition is observed on the RXx line following the wake-up event. At this point, the EUSART module is in Idle mode and returns to normal operation. This signals to the user that the Sync Break event is over.

21.2.4.1 Special Considerations Using Auto-Wake-up

Since auto-wake-up functions by sensing rising edge transitions on RXx/DTx, information with any state changes before the Stop bit may signal a false End-Of-Character (EOC) and cause data or framing errors. To work properly, therefore, the initial character in the transmission must be all '0's. This can be 00h (8 bits) for standard RS-232 devices or 000h (12 bits) for LIN/J2602 bus.

Oscillator start-up time must also be considered, especially in applications using oscillators with longer start-up intervals (i.e., HS or HSPLL mode). The Sync Break (or Wake-up Signal) character must be of sufficient length and be followed by a sufficient interval to allow enough time for the selected oscillator to start and provide proper initialization of the EUSART.

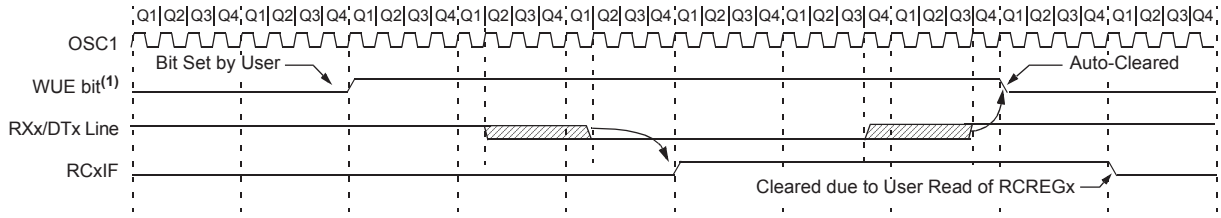
21.2.4.2 Special Considerations Using the WUE Bit

The timing of WUE and RCxIF events may cause some confusion when it comes to determining the validity of received data. As noted, setting the WUE bit places the EUSART in an Idle mode. The wake-up event causes a receive interrupt by setting the RCxIF bit. The WUE bit is cleared after this when a rising edge is seen on RXx/DTx. The interrupt condition is then cleared by reading the RCREGx register. Ordinarily, the data in RCREGx will be dummy data and should be discarded.

The fact that the WUE bit has been cleared (or is still set) and the RCxIF flag is set should not be used as an indicator of the integrity of the data in RCREGx. Users should consider implementing a parallel method in firmware to verify received data integrity.

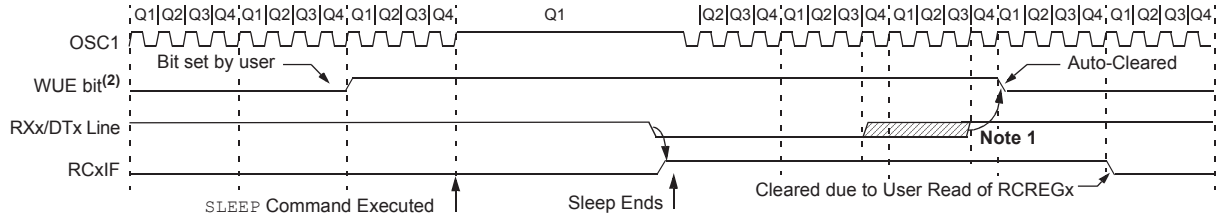
To assure that no actual data is lost, check the RCIDL bit to verify that a receive operation is not in process. If a receive operation is not occurring, the WUE bit may then be set just prior to entering Sleep mode.

FIGURE 21-8: AUTO-WAKE-UP BIT (WUE) TIMINGS DURING NORMAL OPERATION



Note 1: The EUSART remains in Idle while the WUE bit is set.

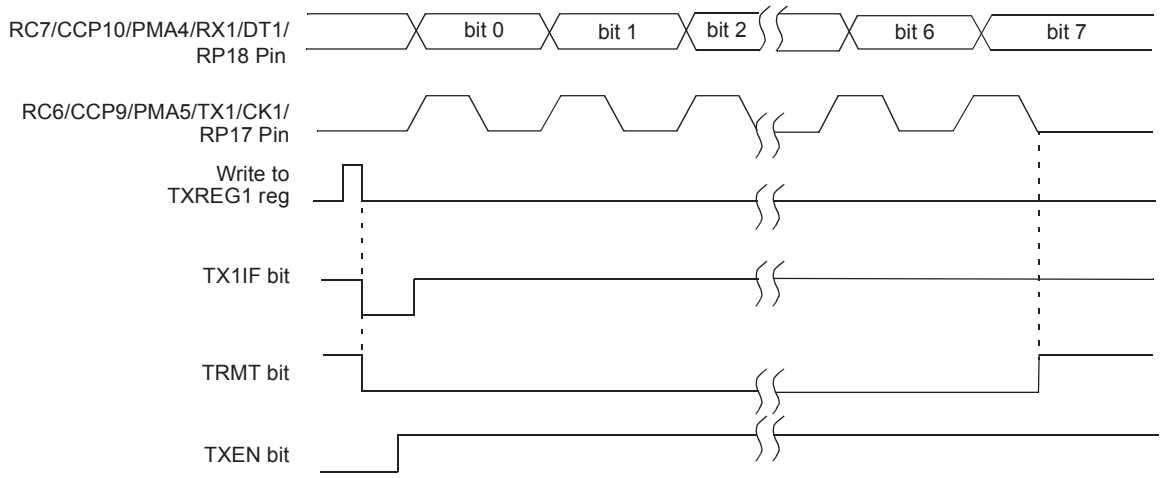
FIGURE 21-9: AUTO-WAKE-UP BIT (WUE) TIMINGS DURING SLEEP



Note 1: If the wake-up event requires long oscillator warm-up time, the auto-clear of the WUE bit can occur before the oscillator is ready. This sequence should not depend on the presence of Q clocks.

2: The EUSART remains in Idle while the WUE bit is set.

FIGURE 21-12: SYNCHRONOUS TRANSMISSION (THROUGH TXEN)



Note: This example is equally applicable to EUSART2 (RPn1/TX2/CK2 and RPn2/RX2/DT2).

TABLE 21-7: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF
PIR1	PMPIF(1)	ADIF	RC1IF	TX1IF	SSP1IF	CCP1IF	TMR2IF	TMR1IF
PIE1	PMPIE(1)	ADIE	RC1IE	TX1IE	SSP1IE	CCP1IE	TMR2IE	TMR1IE
IPR1	PMPIP(1)	ADIP	RC1IP	TX1IP	SSP1IP	CCP1IP	TMR2IP	TMR1IP
PIR3	SSP2IF	BCL2IF	RC2IF	TX2IF	TMR4IF	CTMUIF	TMR3GIF	RTCCIF
PIE3	SSP2IE	BCL2IE	RC2IE	TX2IE	TMR4IE	CTMUIE	TMR3GIE	RTCCIE
IPR3	SSP2IP	BCL2IP	RC2IP	TX2IP	TMR4IP	CTMUIP	TMR3GIP	RTCCIP
RCSTAx	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
TXREGx	EUSARTx Transmit Register							
TXSTAx	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D
BAUDCONx	ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	—	WUE	ABDEN
SPBRGHx	EUSARTx Baud Rate Generator High Byte							
SPBRGx	EUSARTx Baud Rate Generator Low Byte							
ODCON2	—	—	—	—	CCP10OD	CCP9OD	U2OD	U1OD

Legend: — = unimplemented, read as '0'. Shaded cells are not used for synchronous master transmission.

Note 1: These pins are only available on 44-pin devices.

21.3.2 EUSART SYNCHRONOUS MASTER RECEPTION

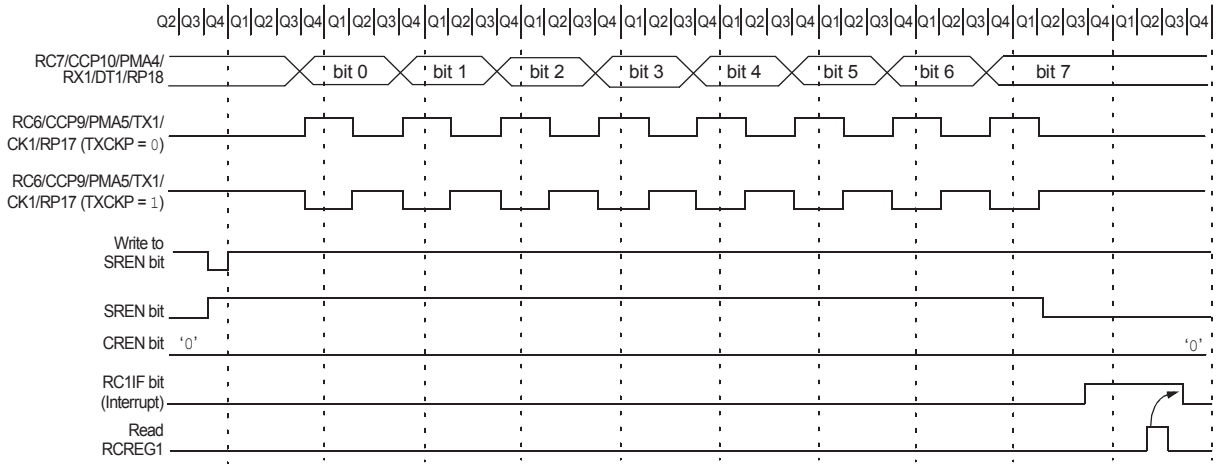
Once Synchronous mode is selected, reception is enabled by setting either the Single Receive Enable bit, SREN (RCSTAx<5>), or the Continuous Receive Enable bit, CREN (RCSTAx<4>). Data is sampled on the RXx pin on the falling edge of the clock.

If enable bit, SREN, is set, only a single word is received. If enable bit, CREN, is set, the reception is continuous until CREN is cleared. If both bits are set, then CREN takes precedence.

To set up a Synchronous Master Reception:

1. Initialize the SPBRGHx:SPBRGx registers for the appropriate baud rate. Set or clear the BRG16 bit, as required, to achieve the desired baud rate.
2. Enable the synchronous master serial port by setting bits, SYNC, SPEN and CSRC.
3. Ensure bits, CREN and SREN, are clear.
4. If interrupts are desired, set enable bit, RCxIE.
5. If 9-bit reception is desired, set bit, RX9.
6. If a single reception is required, set bit, SREN. For continuous reception, set bit, CREN.
7. Interrupt flag bit, RCxIF, will be set when reception is complete and an interrupt will be generated if the enable bit, RCxIE, was set.
8. Read the RCSTAx register to get the ninth bit (if enabled) and determine if any error occurred during reception.
9. Read the 8-bit received data by reading the RCREGx register.
10. If any error occurred, clear the error by clearing bit, CREN.
11. If using interrupts, ensure that the GIE and PEIE bits in the INTCON register (INTCON<7:6>) are set.

FIGURE 21-13: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note: Timing diagram demonstrates Sync Master mode with bit, SREN = 1, and bit, BRGH = 0. This example is equally applicable to EUSART2 (RPn1/TX2/CK2 and RPn2/RX2/DT2).

BNC **Branch if Not Carry**

Syntax: BNC n

Operands: -128 ≤ n ≤ 127

Operation: if Carry bit is '0',
(PC) + 2 + 2n → PC

Status Affected: None

Encoding:

1110	0011	nnnn	nnnn

Description: If the Carry bit is '0', then the program will branch.

The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example: HERE BNC Jump

Before Instruction
PC = address (HERE)
After Instruction
If Carry = 0;
PC = address (Jump)
If Carry = 1;
PC = address (HERE + 2)

BNN **Branch if Not Negative**

Syntax: BNN n

Operands: -128 ≤ n ≤ 127

Operation: if Negative bit is '0',
(PC) + 2 + 2n → PC

Status Affected: None

Encoding:

1110	0111	nnnn	nnnn

Description: If the Negative bit is '0', then the program will branch.

The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example: HERE BNN Jump

Before Instruction
PC = address (HERE)
After Instruction
If Negative = 0;
PC = address (Jump)
If Negative = 1;
PC = address (HERE + 2)

CLRF **Clear f**

Syntax: CLRF f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: 000h → f,
1 → Z

Status Affected: Z

Encoding:

0110	101a	ffff	ffff

Description: Clears the contents of the specified register.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 28.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: CLRF FLAG_REG,1

Before Instruction
FLAG_REG = 5Ah
After Instruction
FLAG_REG = 00h

CLRWDT **Clear Watchdog Timer**

Syntax: CLRWDT

Operands: None

Operation: 000h → WDT,
000h → WDT postscaler,
1 → $\overline{TO}$,
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

0000	0000	0000	0100

Description: CLRWDT instruction resets the Watchdog Timer. It also resets the postscaler of the WDT. Status bits, $\overline{TO}$ and $\overline{PD}$, are set.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	Process Data	No operation

Example: CLRWDT

Before Instruction
WDT Counter = ?
After Instruction
WDT Counter = 00h
WDT Postscaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

MOVFF **Move f to f**

Syntax: MOVFF f_s,f_d

Operands: $0 \le f_s \le 4095$
$0 \le f_d \le 4095$

Operation: $(f_s) \rightarrow f_d$

Status Affected: None

Encoding:

1st word (source)	1100	ffff	ffff	$ffff_s$
2nd word (destin.)	1111	ffff	ffff	$ffff_d$

Description: The contents of source register 'f_s' are moved to destination register 'f_d'. Location of source 'f_s' can be anywhere in the 4096-byte data space (000h to FFFh) and location of destination 'f_d' can also be anywhere from 000h to FFFh.

Either source or destination can be W (a useful special situation).

MOVFF is particularly useful for transferring a data memory location to a peripheral register (such as the transmit buffer or an I/O port).

The MOVFF instruction cannot use the PCL, TOSU, TOSH or TOSL as the destination register

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f' (src)	Process Data	No operation
Decode	No operation No dummy read	No operation	Write register 'f' (dest)

Example: MOVFF REG1, REG2

Before Instruction
REG1 = 33h
REG2 = 11h
After Instruction
REG1 = 33h
REG2 = 33h

MOVLB **Move Literal to Low Nibble in BSR**

Syntax: MOVLW k

Operands: $0 \le k \le 255$

Operation: $k \rightarrow BSR$

Status Affected: None

Encoding:

0000	0001	kkkk	kkkk

Description: The 8-bit literal 'k' is loaded into the Bank Select Register (BSR). The value of BSR<7:4> always remains '0' regardless of the value of k_7:k_4.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write literal 'k' to BSR

Example: MOVLB 5

Before Instruction
BSR Register = 02h
After Instruction
BSR Register = 05h

TSTFSZ **Test f, Skip if 0**

Syntax: TSTFSZ f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: skip if f = 0

Status Affected: None

Encoding:

0110	011a	ffff	ffff

Description: If 'f' = 0, the next instruction fetched during the current instruction execution is discarded and a NOP is executed, making this a 2-cycle instruction.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 28.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    TSTFSZ  CNT, 1
NZERO   :
ZERO    :
```
Before Instruction
PC = Address (HERE)
After Instruction
If CNT = 00h,
PC = Address (ZERO)
If CNT ≠ 00h,
PC = Address (NZERO)

XORLW **Exclusive OR Literal with W**

Syntax: XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → W

Status Affected: N, Z

Encoding:

0000	1010	kkkk	kkkk

Description: The contents of W are XORed with the 8-bit literal 'k'. The result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to W

Example:
```
XORLW   0xAF
```
Before Instruction
W = B5h
After Instruction
W = 1Ah

28.2.3 BYTE-ORIENTED AND BIT-ORIENTED INSTRUCTIONS IN INDEXED LITERAL OFFSET MODE

Note: Enabling the PIC18 instruction set extension may cause legacy applications to behave erratically or fail entirely.

In addition to eight new commands in the extended set, enabling the extended instruction set also enables Indexed Literal Offset Addressing (**Section 6.6.1 "Indexed Addressing with Literal Offset"**). This has a significant impact on the way that many commands of the standard PIC18 instruction set are interpreted.

When the extended set is disabled, addresses embedded in opcodes are treated as literal memory locations: either as a location in the Access Bank (a = 0) or in a GPR bank designated by the BSR (a = 1). When the extended instruction set is enabled and a = 0, however, a file register argument of 5Fh or less is interpreted as an offset from the pointer value in FSR2 and not as a literal address. For practical purposes, this means that all instructions that use the Access RAM bit as an argument – that is, all byte-oriented and bit-oriented instructions, or almost half of the core PIC18 instructions – may behave differently when the extended instruction set is enabled.

When the content of FSR2 is 00h, the boundaries of the Access RAM are essentially remapped to their original values. This may be useful in creating backward-compatible code. If this technique is used, it may be necessary to save the value of FSR2 and restore it when moving back and forth between C and assembly routines in order to preserve the Stack Pointer. Users must also keep in mind the syntax requirements of the extended instruction set (see **Section 28.2.3.1 "Extended Instruction Syntax with Standard PIC18 Commands"**).

Although the Indexed Literal Offset mode can be very useful for dynamic stack and pointer manipulation, it can also be very annoying if a simple arithmetic operation is carried out on the wrong register. Users who are accustomed to the PIC18 programming must keep in mind that, when the extended instruction set is enabled, register addresses of 5Fh or less are used for Indexed Literal Offset Addressing.

Representative examples of typical byte-oriented and bit-oriented instructions in the Indexed Literal Offset mode are provided on the following page to show how execution is affected. The operand conditions shown in the examples are applicable to all instructions of these types.

28.2.3.1 Extended Instruction Syntax with Standard PIC18 Commands

When the extended instruction set is enabled, the file register argument, 'f', in the standard byte-oriented and bit-oriented commands is replaced with the literal offset value, 'k'. As already noted, this occurs only when 'f' is less than or equal to 5Fh. When an offset value is used, it must be indicated by square brackets ("[ ]"). As with the extended instructions, the use of brackets indicates to the compiler that the value is to be interpreted as an index or an offset. Omitting the brackets, or using a value greater than 5Fh within the brackets, will generate an error in the MPASM Assembler.

If the index argument is properly bracketed for Indexed Literal Offset Addressing, the Access RAM argument is never specified; it will automatically be assumed to be '0'. This is in contrast to standard operation (extended instruction set disabled), when 'a' is set on the basis of the target address. Declaring the Access RAM bit in this mode will also generate an error in the MPASM Assembler.

The destination argument 'd' functions as before.

In the latest versions of the MPASM Assembler, language support for the extended instruction set must be explicitly invoked. This is done with either the command line option, /y, or the PE directive in the source listing.

28.2.4 CONSIDERATIONS WHEN ENABLING THE EXTENDED INSTRUCTION SET

It is important to note that the extensions to the instruction set may not be beneficial to all users. In particular, users who are not writing code that uses a software stack may not benefit from using the extensions to the instruction set.

Additionally, the Indexed Literal Offset Addressing mode may create issues with legacy applications written to the PIC18 assembler. This is because instructions in the legacy code may attempt to address registers in the Access Bank below 5Fh. Since these addresses are interpreted as literal offsets to FSR2 when the instruction set extension is enabled, the application may read or write to the wrong data addresses.

When porting an application to the PIC18F47J13 Family, it is very important to consider the type of code. A large, re-entrant application that is written in C and would benefit from efficient compilation will do well when using the instruction set extensions. Legacy applications that heavily use the Access Bank will most likely not benefit from using the extended instruction set.

29.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

29.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

29.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

29.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

29.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

30.1 DC Characteristics: Supply Voltage PIC18F47J13 Family (Industrial)

PIC18F47J13 Family			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	2.15	—	3.6	V	PIC18F4XJ13, PIC18F2XJ13
D001A	VDD	Supply Voltage	2.0	—	3.6	V	PIC18LF4XJ13, PIC18LF2XJ13
D001B	VDDCORE	External Supply for Microcontroller Core	2.0	—	2.75	V	PIC18LF4XJ13, PIC18LF2XJ13
D001C	AVDD	Analog Supply Voltage	VDD – 0.3	—	VDD + 0.3	V	
D001D	AVSS	Analog Ground Potential	VSS – 0.3	—	VSS + 0.3	V	
D002	VDR	RAM Data Retention Voltage(1)	1.5	—	—	V	
D003	VPOR	VDD Start Voltage to Ensure Internal Power-on Reset Signal	—	—	0.7	V	See **Section 5.3 "Power-on Reset (POR)"** for details
D004	SVDD	VDD Rise Rate to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	See **Section 5.3 "Power-on Reset (POR)"** for details
D005	VBOR	VDDCORE Brown-out Reset Voltage	—	2.0	2.15	V	PIC18F4XJ13, PIC18F2XJ13 only
D006	VDSBOR	VDD Brown-out Reset Voltage	—	1.8	—	V	DSBOREN = 1 on "LF" device or "F" device in Deep Sleep

Note 1: This is the limit to which VDDCORE can be lowered in Sleep mode, or during a device Reset, without losing RAM data.

30.3 DC Characteristics: PIC18F47J13 Family (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial			
Param No.	**Symbol**	**Characteristic**	**Min**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**				
		All I/O Ports:				
D030		with TTL Buffer	VSS	0.15 VDD	V	VDD < 3.3V
D030A		with TTL Buffer	VSS	0.8	V	3.3V ≤ VDD ≤ 3.6V
D031		with Schmitt Trigger Buffer	VSS	0.2 VDD	V	
D031A		SCLx/SDAx	—	0.3 VDD	V	I^2C enabled
D031B		SCLx/SDAx	—	0.8	V	SMBus enabled
D032		$\overline{MCLR}$	VSS	0.2 VDD	V	
D033		OSC1	VSS	0.3 VDD	V	HS, HSPLL modes
D033A		OSC1	VSS	0.2 VDD	V	EC, ECPLL modes
D034		T1OSI	VSS	0.3	V	T1OSCEN = 1
	VIH	**Input High Voltage**				
		I/O Ports without 5.5V Tolerance:				
D040		with TTL Buffer	0.25 VDD + 0.8V	VDD	V	VDD < 3.3V
D040A		with TTL Buffer	2.0	VDD	V	3.3V ≤ VDD ≤ 3.6V
D041		with Schmitt Trigger Buffer	0.8 VDD	VDD	V	
		I/O Ports with 5.5V Tolerance:(4)				
Dxxx		with TTL Buffer	0.25 VDD + 0.8V	5.5	V	VDD < 3.3V
DxxxA			2.0	5.5	V	3.3V ≤ VDD ≤ 3.6V
Dxxx		with Schmitt Trigger Buffer	0.8 VDD	5.5	V	
D041A		SCLx/SDAx	0.7 VDD	—	V	I^2C enabled
D041B		SCLx/SDAx	2.1	—	V	SMBus enabled; VDD ≥ 3V
D042		$\overline{MCLR}$	0.8 VDD	5.5	V	
D043		OSC1	0.7 VDD	VDD	V	HS, HSPLL modes
D043A		OSC1	0.8 VDD	VDD	V	EC, ECPLL modes
D044		T1OSI	1.6	VDD	V	T1OSCEN = 1
	IPU	**Weak Pull-up Current**				
D070	IPURB	PORTB, PORTD(3) and PORTE(3) Weak Pull-up Current	80	400	μA	VDD = 3.3V, VPIN = VSS

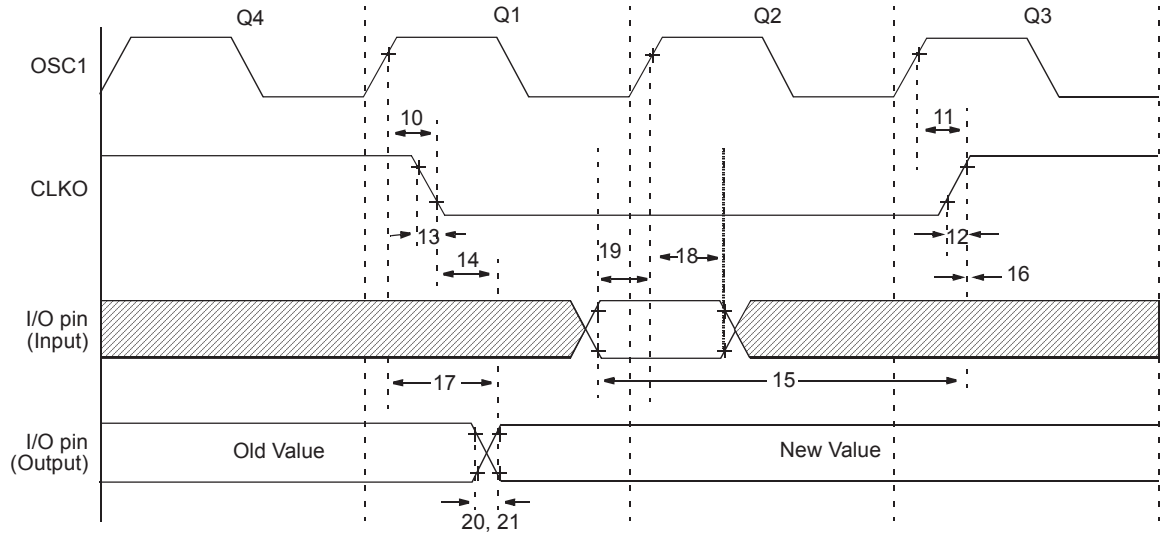
Note 1: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: Only available in 44-pin devices.

4: Refer to Table 10-2 for pin tolerance levels.

FIGURE 30-6: CLKO AND I/O TIMING



Note: Refer to Figure 30-4 for load conditions.

TABLE 30-13: CLKO AND I/O TIMING REQUIREMENTS

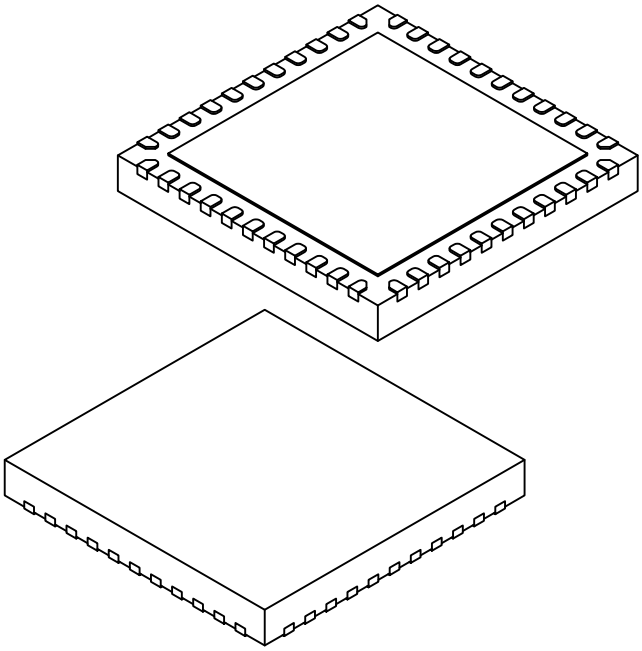
Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
10	TOSH2CKL	OSC1 ↑ to CLKO ↓	—	75	200	ns	**(Note 1)**
11	TOSH2CKH	OSC1 ↑ to CLKO ↑	—	75	200	ns	**(Note 1)**
12	TCKR	CLKO Rise Time	—	15	30	ns	**(Note 1)**
13	TCKF	CLKO Fall Time	—	15	30	ns	**(Note 1)**
14	TCKL2IOV	CLKO ↓ to Port Out Valid	—	—	0.5 TCY + 20	ns	
15	TIOV2CKH	Port In Valid before CLKO ↑	0.25 TCY + 25	—	—	ns	
16	TCKH2IOI	Port In Hold after CLKO ↑	0	—	—	ns	
17	TOSH2IOV	OSC1 ↑ (Q1 cycle) to Port Out Valid	—	50	150	ns	
18	TOSH2IOI	OSC1 ↑ (Q2 cycle) to Port Input Invalid (I/O in hold time)	100	—	—	ns	
19	TIOV2OSH	Port Input Valid to OSC1 ↑ (I/O in setup time)	0	—	—	ns	
20	TIOR	Port Output Rise Time	—	—	6	ns	
21	TIOF	Port Output Fall Time	—	—	5	ns	
22†	TINP	INTx pin High or Low Time	TCY	—	—	ns	
23†	TRBP	RB<7:4> Change INTx High or Low Time	TCY	—	—	ns	

† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in EC mode, where CLKO output is 4 x TOSC.

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN or VQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103D Sheet 2 of 2